

EXCESS SILICON

SunEdison Semiconductor produces the highest quality Semiconductor grade Silicon ingots and Silicon wafers. We drive innovation and strict quality control at every step of the value chain to ensure maximum quality and consistency. Due to our high volume manufacturing, SunEdison Semiconductor generates excess silicon materials, which companies can use for a variety of applications. This high quality material can provide companies with cost effective solutions while enjoying the benefits of using good quality material in their manufacturing process.





MATERIAL MASTER	DESCRIPTION
BIN 1 P Type Resistivity > 1 Ohm Cm (Purity 99.99%)(Net Kgs)	
SLRXXSGP1	Silicon Slugs - Thick sections cut from ingots to conduct testing; same high quality as Silicon Ingot
SLRTATP1	Crystal - Tops/Tails
SLRTATNP1	Crystal - Tops/Tails - Nitrogen Doped
SLRCRYSP1	Crystal - LZD Pieces
SLRCRYSNP1	Crystal - LZD Pieces - Nitrogen Doped
SLRAGDP1	Ingot Segments
SLRPOTP1	Potscrap without Quartz - Remaining poly left in the crucible after ingot growth
SLRPOTPR1	Premium Potscrap without Quartz - Remaining High Resistivity Poly left in the crucible after ingot growth
SLRPOTNP1	Nitrogen Doped Potscrap without Quartz - Remaining poly left in the crucible after ingot growth
SLRPOTP2	Potscrap with 40% Quartz - Remaining poly left in the crucible after ingot growth
SLRPOTNP2	Nitrogen Doped Potscrap with 40% Quartz - Remaining poly left in the crucible after ingot growth
BIN 2 N Type Resistivity > 1 Ohm Cm (Purity 99.99%)(Net Kgs)	
SLRXXSGN1	Si Slugs - Thick sections cut from ingots to conduct testing; same high quality as Silicon Ingot
SLRTATN1	Crystal - Tops/Tails
SLRCRYSN1	Crystal - LZD Pieces
SLRAGDN1	Ingot Segments
SLRPOTN1	Potscrap without Quartz - Remaining poly left in the crucible after ingot growth
SLRPOTN2	Potscrap with 40% Quartz - Remaining poly left in the crucible after ingot growth
BIN 3 P+, P++, N+ Mix of Bin 1(P Type) and Bin 2(N Type) and types with known and unknown resistivity (Net Kgs)	
SCRXXSGSI	Si Slugs - Thick sections cut from ingots to conduct testing; same high quality as Silicon Ingot
SCRTATSI	Crystal - Tops/Tails
SCRCRYSSI	Crystal - LZD Pieces
SCRAGDSI	Ingot Segments
SCRPOTSI	Potscrap with 40% Quartz - Remaining poly left in the crucible after ingot growth
SCRPOTS2	Potscrap without Quartz - Remaining poly left in the crucible after ingot growth
SCRPOTS3	Potscrap with 75% Quartz - Remaining poly left in the crucible after ingot growth



Coin Roll



Coin Roll with Film



Broken Wafers



Broken Wafers with Pattern



Slurry Wafers

MATERIAL MASTER	DESCRIPTION
BIN 1 P Type Resistivity > 1 Ohm Cm (Purity 99.99%)(Net Kgs)	
SLR15SLP1	150mm Coin Roll
SLR20SLP1	200mm Coin Roll
SLR30SLP1	300mm Coin Roll
SLRXXSLP1	Mixed Diameter Coin Roll
SLRXXPTN	Pattern/Film/LTO Coin Roll
SLRBRKSLP1	Broken Wafers
SLRBRKPTN	Pattern/Film/LTO Broken Wafer
BIN 2 N Type Resistivity > 1 Ohm Cm (Purity 99.99%)(Net Kgs)	
SLR15SLN1	150mm Coin Roll
SLR20SLN1	200mm Coin Roll
SLRXXSLN1	Mixed Diameter Coin Roll
SLRBRKSLN1	Broken Wafers
BIN 3 P+, P++, N+ Mix of Bin 1(P Type) and Bin 2(N Type) and types with known and unknown resistivity (Net Kgs)	
SCR15SLS	150mm Coin Roll
SCR20SLS	200mm Coin Roll
SCR30SLS	300mm Coin Roll
SCRXXSLS	Mixed Diameter Coin Roll
SCRXXPTN	Pattern/Film/LTO Coin Roll
SCRBRKSI	Broken Wafers
SCRBRKPTN	Pattern/Film/LTO Broken Wafer